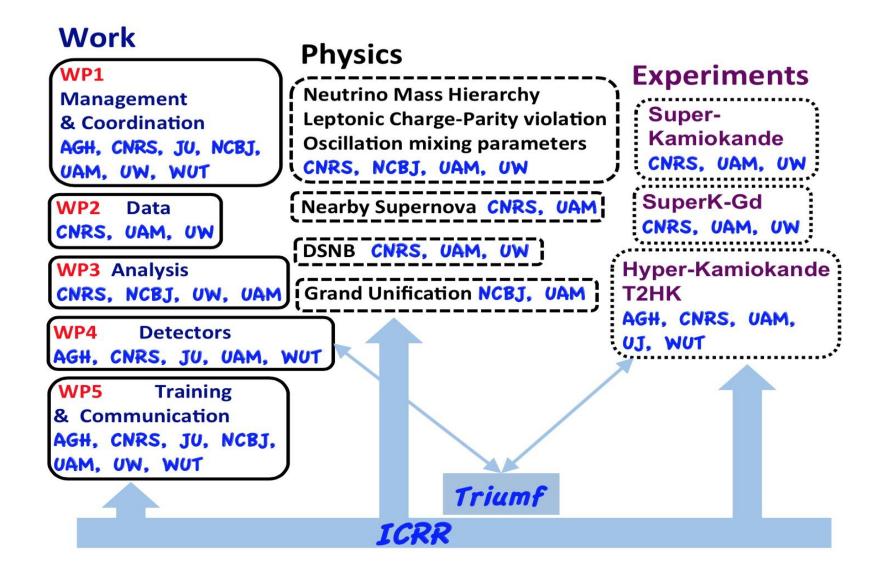
The SK2HK « Rise » european grant

O.Drapier, réunion de groupe January 21st, 2020

The SK2HK project



Our committments: Participation to « work packages » « Deliverables » « Secondments »

- Deliverables are
 - Documents (theses, reports)
 - Organization of meetings, workshops
 - Organization of either a general HK collaboration meeting, or the
 « II European Workshop on Water Cherenkov Precision Detectors for Neutrinos and Nucleon Decay »
- Secondements are travels to ICRR, related to the transition SK ightarrow HK
 - SK, SK-Gd SHIFTS, TOKAI SHIFTS EXCLUDED (T2K shifts @ SK ~ OK)
 - Any work related to HK or T2HK (HK coll. meeting excluded if alone)
 - HK Coll meeting + on site work to prepare HK : eligible

WP1: Management and coordination

- Task 1.2: Organization of 5 meetings
 - All institutes involved

• WP2: Data

- Task 2.2: lead data taking with SK/Gd
 - EP, UAM and UW heavily involved

WP3: Analysis

- Lead by EP, see Sonia's talk
- Task 3.1: lead DSNB searches
 - UAM and UW involved
- Task 3.3: supervise 2 PhD works on Low E
 - Raleted to task 5.1 (WP5)

LLR Responsibilities in SK2HK Work Packages

- WP4: Detectors
 - Task 4.4: Lead development of a « cone generator »
 - Efficiency for π ° reconstruction
- WP5: Communication and training
 - Task 5.3: organize the "II European Workshop on Water Cherenkov Precision Detectors

for Neutrino and Nucleon Decay Physics" in France or Spain

What do we get? How does it work?

- ~ 145 (170) k€ Total over 4 years
- Each time a SINGLE PERSON cumulates ONE MONTH in Japan :
 - 2100 € for travel and accomodation expenses
 - 1800 € for other expenses :
 - networking/training/WP work/outreach/...
 - (+700 €) for administrative support (CNRS / LAB)
- We must try to spend part of the expenses from the SK2HK budget WITHOUT overshooting this budget
- If we do not effectively perform the travels, no problem BUT the corresponding money returns to EU!!
- Travel must be eligible
- Must have « SK2HK » in the title
- Please KEEP ALL papers, receipts, proofs, etc ..

Status of the Super-FGD electronics

O.Drapier, réunion de groupe January 21st, 2020

summary

- General status
- LV power distribution
- Some facts concerning mechanics
- Overall setup for crates and cable connection
- Other topics

General status (meeting every other Friday)

- FEB desing under way: technical meetings every Thursday between LLR (Hardware) and UniGe: (Firmware)
 - Need level translators for FPGA / citiroc communication
 - FPGA: 1.8V / not usable for CITI: 3.3 ↔ 1.8V translators under study
 - Adjustable delays in the FPGA: 35ps steps (S. Cap)
 - Reprogramming the FPGA remotely (S. Cap)
 - Citiroc news: Two months delay for mass prod
 - Many chips available for prototypes, so no incidence on schedule
- Backplanes and Optical Concentrators → U.S. groups
 - Starting soon to discuss detailed interfaces
 - List needed lines in Digital Backplane
- DAQ ? Sync / Clk board ? To be discussed (UniGe ?)

LV power

- One FEB LV needs:
 - 1.1 V 4.5 A
 - 3.8 V 2.7 A
 - 5.3 V 0.5 A
 - - 3.8 V 1.1 A
- U.S. groups in charge of finding a solution (critical):
 - External PS ? → CABLES !!!
 - In-magnet LV Modules ? → HIGH CURRENT / VERY BIG AIR COILS !!!
 - On-board DC/DCs ? → NOISE / QUITE BIG AIR COILS !!!
- Any mix of these? Need to test in-field behavior, need to precisely evaluate possibility for external cables
- Decision made of a mezzanine board:
 - Designed @ U.Pittsburgh
 - Prototype FEB could host the LV mezzanine
 - Integrated on board for final production, if proven to work

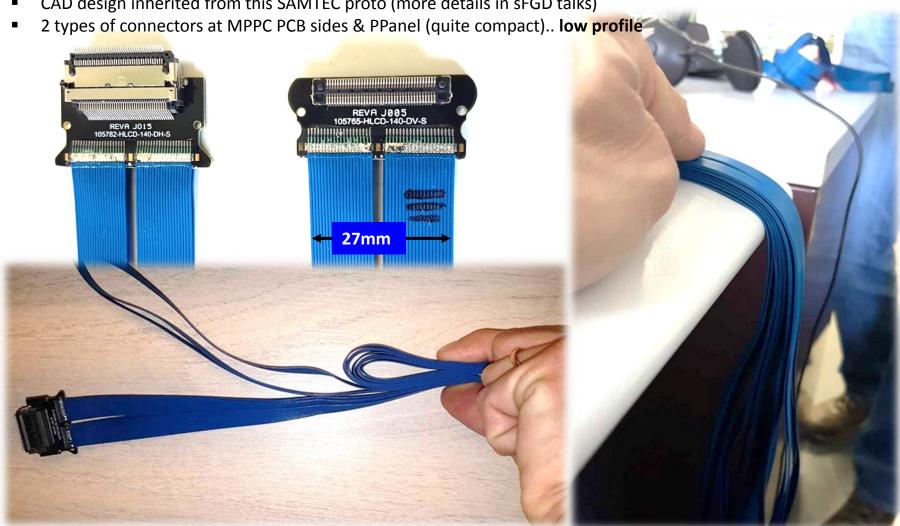
Analog cables

Bending the cables:

Radius = 0.125" ~ a pen

FEB & Cable design



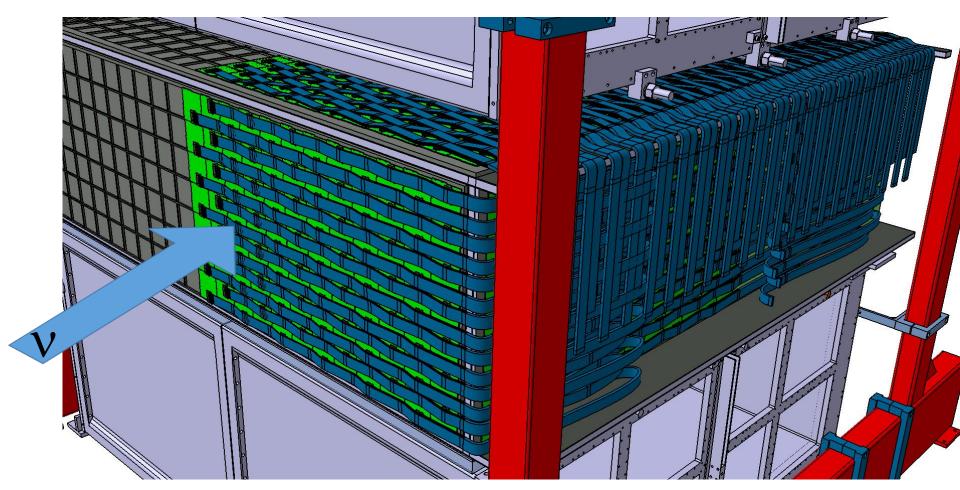


Cable bundles



FEB Design & Crate size assessment

Reminder of cable bundle envelopes



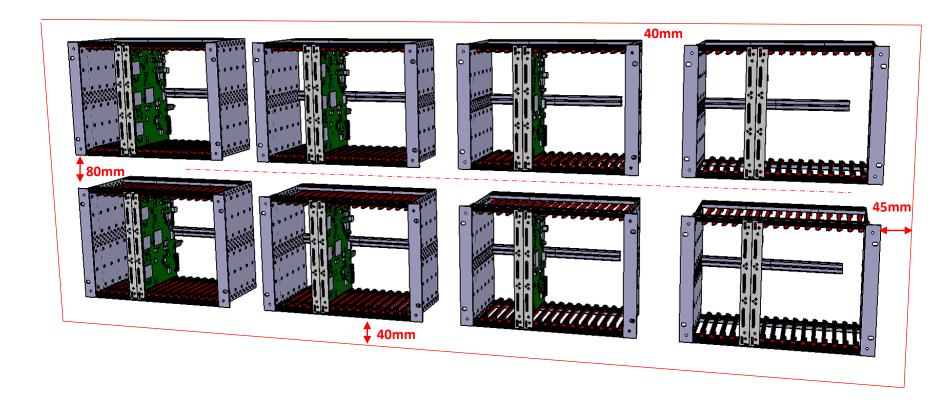
Crates



FEB Design & Crate size assessment

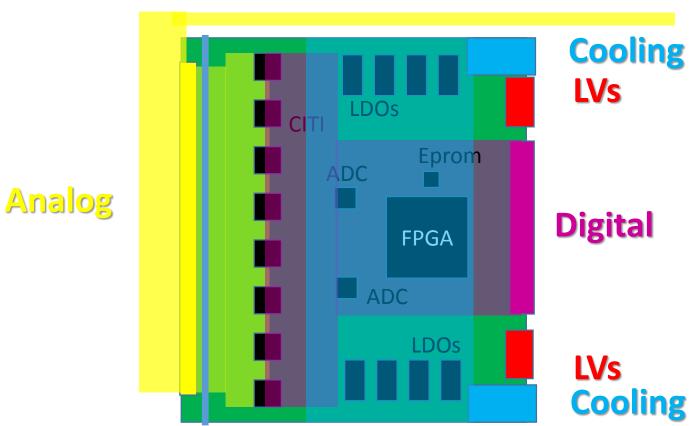
Based on past experience (CTA camera and Baby MIND)

- Extrapolation to the sFGD side assembly (2 rows, each crate is centred / envelope)
- Envelope that is used / sFGD: **1900mm x 692mm x 300mm** (80mm is taken for cables)

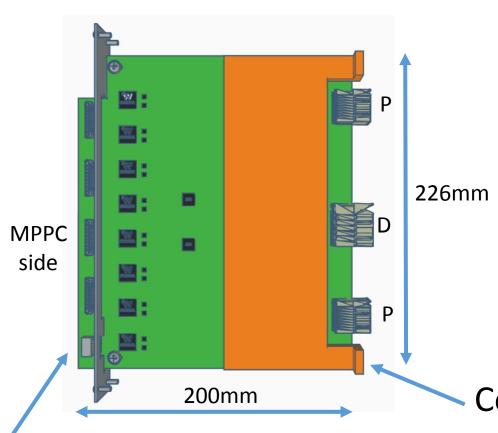


Improved version

- LVs and digital connectors to backplane, at the rear
- Analog connectors on board extension going through front panel
- Cooling at the rear, no need to remove circuit, larger board
- Cooling bar closer to the heat sources
- No reduction of board area



FEB mechanical design (next slides by J. Nanni)



Baseline FEB design:

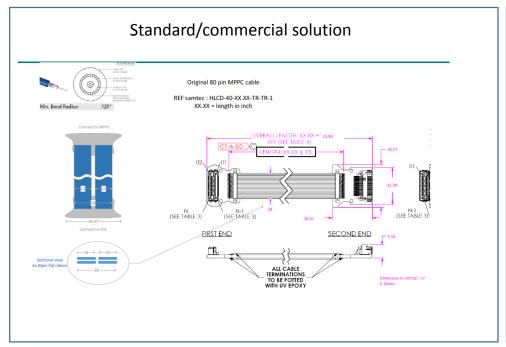
- 8 CITIROC
- 2 ADC
- 1 digital connector
- "2 power connectors" ?
- 4 analog connectors

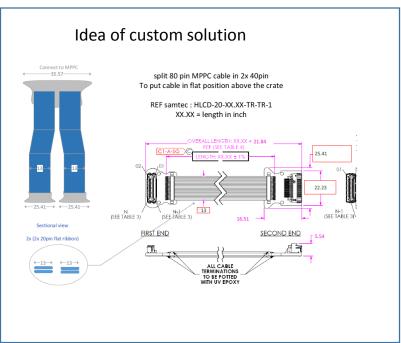
Copper plate for cooling

Test connector



oposal to split analog cables









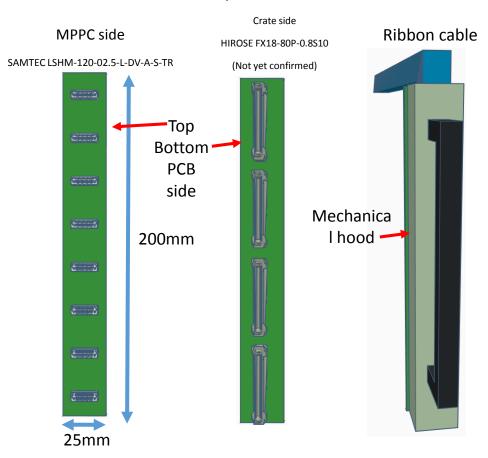
Specifications: Design of a PCB front plane

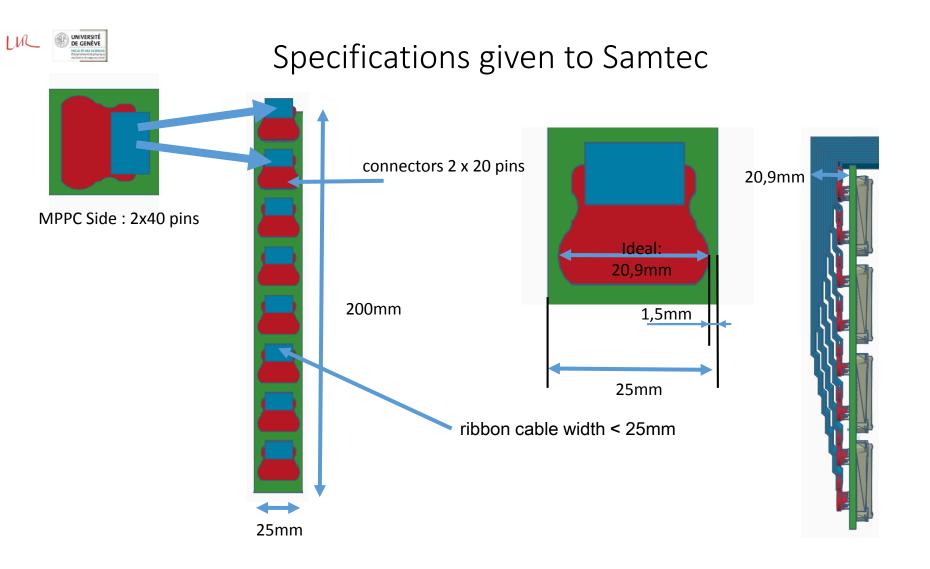
Advantages:

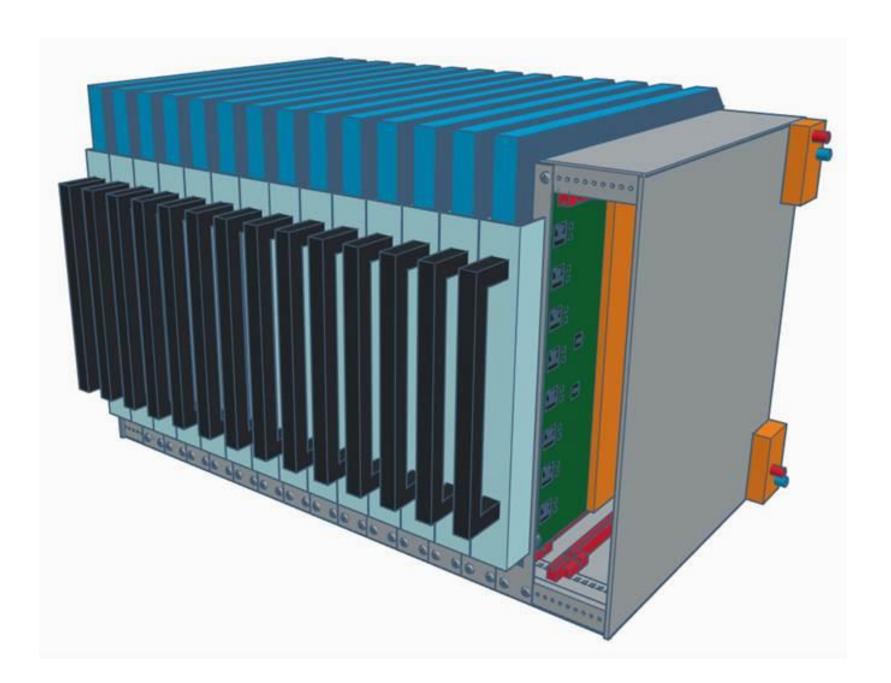
- ➤ Easy to plug/unplug on the dedicated FEB
- ➤ No risk of damage to the analog cable

Constraints:

- ➤ Needs high precision
- Strength ? Need for screws/clips ?







Other topics

- Critical: think seriously about analog cable routing
- Critical: make decision concerning cables from outside for high currents (room for PS near the magnet ? B field there ?)
- Critical: calculate precise heat dissipation and cooling power together with pipe routing
- Critical: start studying the mechanical structure
- Critical: prepare a plan for installation!
- Sign a final collaboration agreement UniGe ↔ LLR
- Sign NDA UniGe ↔ U.S. groups
- Prepare a plan for test benche(s)
- Share DAQ + Clk/Sync responsibilities